

Atty Ref/Docket No.: 884.418US1

07-25-2001



101787599

To the Honorable Commissioner of Patents and Trademark

Original documents or copy thereof.

1. Name of conveying party(ies):

Steven Towle, Hajime Sakamoto and Dongdong Wang

Additional name(s) of conveying party(ies) attached? []Yes [X]No

3. Nature of conveyance:

- Assignment
- Merger
- Security Agreement
- Change of Name
- Other _____

Execution Date: June 25, 2001, June 20, 2001, June 20, 2001

2. Name and address of receiving party(ies):

Name: Intel Corporation
Street Address: 2625 Walsh Avenue
City: Santa Clara State: CA ZIP: 95051

AND

Name: Ibiden Company Limited
2-1, Kanda-machi, Ogaki
Gifu Prefecture, 503, Japan

Additional name(s) & address(es) attached? []Yes [X]No



4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: June 25, 2001, June 20, 2001, June 20, 2001

A. Patent Application No.(s)

B. Patent No.(s)

09/903025

Additional numbers attached? []Yes [X]No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Ann M. McCrackin

Address: Schwegman, Lundberg, Woessner & Kluth, P.A.
P.O. Box 2938
Minneapolis, MN 55402

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):\$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Please charge any additional fees or credit any overpayments to our
Deposit account number: 19-0743

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ann M. McCrackin/Reg. No. 42,858
Name of Person Signing

Ann M. McCrackin
Signature

July 11, 2001
Date

Total number of pages including cover sheet: 5

OMB No. 0651-0011 (exp. 4/94)

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ASSIGNMENT

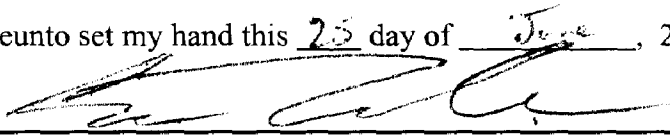
WHEREAS, WE, Steven Towle, residing at 301 West Desert Flower Lane, Phoenix, Arizona 85045, Hajime Sakamoto, residing at 762-29 18-jyo, Sunami-cho, Motosu-gun, Gifu-ken 501-0314, Japan, and Dongdong Wang, residing at 210, Ishikawahaitsu, Hayashi-machi, Ogaki, Gifu-Pref., 10-82-2, Japan, made certain new and useful inventions and improvements for which we executed an application for Letters Patent of the United States on Even Date Herewith, which is entitled METHOD FOR FABRICATING A MICROELECTRONIC DEVICE USING WAFER-LEVEL ADHESION LAYER DEPOSITION.

AND WHEREAS, Intel Corporation, a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 2625 Walsh Avenue, Santa Clara, CA 95051, and Ibiden Company Limited, a corporation organized and existing under and by virtue of the laws of Japan, having an office and place of business at 2-1, Kanda-machi, Ogaki, Gifu Prefecture, 503, Japan (hereinafter "Assignees") are desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignees, their successors or assigns, in an equal, undivided portion to each of said Assignees, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to said Assignees as the assignees of the entire right, title and interest in and to the same, for the use of said Assignees, their successors and assigns.

AND, furthermore we covenant and agree with said Assignee, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me/us and that full right to convey the same as herein expressed is possessed by us.

IN TESTIMONY WHEREOF, I have hereunto set my hand this 25 day of June, 2001.



Steven Towle

IN TESTIMONY WHEREOF, I have hereunto set my hand this ____ day of _____, 2001.

Hajime Sakamoto

IN TESTIMONY WHEREOF, I have hereunto set my hand this ____ day of _____, 2001.

Dongdong Wang

H.S.
D.W

ASSIGNMENT

WHEREAS, WE, Steven Towle, residing at 301 West Desert Flower Lane, Phoenix, Arizona 85045, Haiime Sakamoto, residing at 762-29 18-jyo, Sunami-cho, Motoyuu-gun, Gifu-ken 501-0314, Japan, and Dongdong Wang, residing at 210, Ishikawahaitsu, Hayashi-machi, Ogaki, Gifu-Pref. 10-82-2, Japan, made certain new and useful inventions and improvements for which we executed an application for Letters Patent of the United States on Even Date Herewith, which is entitled METHOD FOR FABRICATING A MICROELECTRONIC DEVICE USING WAFER-LEVEL ADHESION LAYER DEPOSITION.

AND WHEREAS, Intel Corporation, a corporation organized and existing under and by virtue of the laws of the State of Delaware, and having an office and place of business at 2625 Walsh Avenue, Santa Clara, CA 95051, and Ibiden Company Limited, a corporation organized and existing under and by virtue of the laws of Japan, having an office and place of business at 2-1, Kanda-machi, Ogaki, Gifu Prefecture, 503, Japan (hereinafter "Assignees") are desirous of acquiring the entire right, title and interest in and to said inventions, improvements and application and in and to the Letters Patent to be obtained therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we have sold, assigned, and transferred, and by these presents do sell, assign and transfer unto said Assignees, their successors or assigns, in an equal, undivided portion to each of said Assignees, the entire right, title and interest for all countries in and to all inventions and improvements disclosed in the aforesaid application, and in and to the said application, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and in and to any and all applications which have been or shall be filed in any foreign countries for Letters Patent on the said inventions and improvements, including an assignment of all rights under the provisions of the International Convention, and all Letters Patent of foreign countries which may be granted therefrom; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent for the aforesaid inventions and improvements to said Assignees as the assignees of the entire right, title and interest in and to the same, for the use of said Assignees, their successors and assigns.

Docket No.: ER4.418US1
Serial No.: Not Assigned
Filing Date: Even Date Herewith
Page 7 of 2

AND, for the consideration aforesaid, we do hereby agree that we and our executors and legal representatives will make, execute and deliver any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said Assignees, their successors and representatives all facts known to us relating to said improvements and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable more effectually to secure to and vest in said Assignees, their successors or assigns the entire right, title and interest in and to the said improvements, inventions, applications, Letters Patent, rights, titles, benefits, privileges and advantages hereby sold, assigned and conveyed, or intended so to be.

AND, furthermore we covenant and agree with said Assignees, their successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by me/us and that full right to convey the same as herein expressed is possessed by us.

IN TESTIMONY WHEREOF, I have hereunto set my hand this _____ day of _____, 2001.

Steven Towle

IN TESTIMONY WHEREOF, I have hereunto set my hand this 20 day of June, 2001.

Hajime Sakamoto

Hajime Sakamoto

IN TESTIMONY WHEREOF, I have hereunto set my hand this 20 day of June, 2001.

Dongdong Wang

Dongdong Wang